Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method of producing a joined body ~~of~~including a first member ~~containing~~comprising at least a ~~ceramics~~ceramic and a second member ~~containing~~comprising at least one of a metal ~~or~~and a metal composite~~:~~, ~~the~~said method comprising the steps of~~:~~:

providing ~~an~~a metal adhesive comprising~~composed of a metal containing at least~~ indium and ~~a material containing at least a~~one ~~component capable of reducing the melting point of indium~~tin present in an amount of no more than 10 wt%;

placing said metal adhesive between said first and second members to provide a laminate; and

heating said laminate at a temperature in a solid-liquid coexisting range of an alloy comprising indium and ~~said component~~tin to join said first and second members.

2. (Cancelled).

3. (Currently Amended) The method of claim 1, wherein said laminate is heated at a temperature of not higher than 155°C.

4. (Currently Amended) The method of claim 1, further comprising a step of subjecting~~wherein~~ said laminate to isostatic pressing during said heating step~~is heated while said laminate is subjected to isostatic pressing~~.

5. (Currently Amended) The method of claim 4, further comprising the steps of~~:~~:

vacuum packaging said laminate to form a packaged laminate~~, and~~;

disposingcontaining said packaged laminate in a sealed container filled with an inert gas,; and

subjectingwherein said packaged laminate is subjected to isostatic pressing in said container with said inert gas.

6. (Currently Amended) The method of claim 4, further comprising thea step of reducing the temperature of said laminate to room temperature after said heating stepto room temperature while continuing said isostatic pressing of said laminate is continued.

7. (Currently Amended) The method of claim 1, wherein said metal adhesive has a foil shape of a foil.

8. (Currently Amended) The method of claim 1, wherein said material for reducing melting pointtin is provided between said adhesive indium and said first member.

9. (Currently Amended) The method of claim 1, wherein said material for reducing melting pointtin has one of a foil shape and a film shape of a foil or film.

10. (Original) The method of claim 1, wherein said first member is a semiconductor wafer supporting member.

11. (Currently Amended) The method of claim 10, wherein said semiconductor wafer supporting member is an electrostatic chuck and said second member is a cooling flange.

12. (Currently Amended) The method of claim 1, further comprising the steps of:

providingwherein a first hole is provided in said first member,;

providing a second hole ~~in provided~~ in said second member~~,~~; and ~~said method further comprising the step of~~

providing an air-tight sealing member between said first hole and said adhesive and between said second hole and said adhesive when said first and second members are laminated so that said sealing member directly contacts ~~with~~ said first and second members to provide secure sealing.

13. (Original) A joined body produced by the method of claim 1.

14. (Currently Amended) A joined body comprising:

a first member comprising~~containing~~ at least a ~~ceramics~~,ceramic semiconductor wafer supporting member;

a second member ~~containing~~ comprising at least one of a metal ~~or~~and a metal composite; and

a joining layer provided between said first and second members~~;~~, ~~wherein~~ said joining layer comprising~~comprises a phase of an alloy containing~~ indium and ~~a component capable of reducing the melting point of indium~~ tin present in an amount of no more than 10 wt%.

15. (Cancelled).

16. (Cancelled).

17. (Currently Amended) The joined body of claim ~~16~~14, wherein said semiconductor wafer supporting member is an electrostatic chuck and said second member is a cooling flange.

18. (Currently Amended) The joined body of claim 14, further comprising:

____an air-tight sealing member;; ~~wherein~~

____a first hole ~~is~~ formed in said first member;; and

____a second hole ~~is~~ formed in said second member;;

____wherein said sealing member is provided between said first hole and said joining layer and between said second hole and said joining layer~~, and~~ such that said sealing member directly contacts said first and second members.